ABSTRACT

POLISHING LIQUID AND METHOD FOR POLISHING SUBSTRATE USING THE POLISHING LIQUID

Provided is a polishing liquid including cerium oxide particles, an organic acid A, a polymer compound B having a carboxyl acid group or a carboxylate group, and water, wherein the organic acid A has at least one group selected from the group consisting of -COOM group, -Ph-OM group, $-SO_3M$ group and $-PO_3M_2$ group, pKa of the organic acid A is less than 9, a content of the organic acid A is 0.001 to 1 mass% with respect to the total mass of the polishing liquid, and a content of the polymer compound B is 0.01 to 0.50 mass% with respect to the total mass of the polishing liquid, and pH is in the range of 4.0 to 7.0.

Figure 1